

Metrology Solutions for Wide Band Gap (WBG) Materials

S_WBG_23



About Us

SURAGUS GmbH is a German metrology specialist developing and manufacturing non-contact material testing solutions for thin film materials. Our EddyCus® systems are installed at customer sites on six continents and are serviced and distributed through a worldwide network of sales and service partners. We serve numerous industries applying thin films in a wide variety of processes.

Technology

SURAGUS utilizes a unique high-frequency, wide range eddy current technology. This wide range, high frequency combination enables rapid testing of both very low and highly conductive materials. Our EddyCus® measurement systems (Eddy Current Solutions) excel with high sample rates and in non-contact setups, and come with several industrial interfaces and user-friendly software.

Portfolio

SURAGUS' portfolio comprises hand-held devices, table-sized benchtop testing solutions, robot based systems and standard & customized inline solutions. Standard and customized sensors are used to tailor to a large number of non-contact testing tasks including the measurement of physical parameters and defect detection.

Values


SURAGUS is a customer-focused and technology-driven company. A long-term and result-driven mutual cooperation between our customers and partners is of the highest importance to us. Our interdisciplinary R&D team transforms latest advancements in microelectronics and sensor manufacturing into novel testing solutions for our customers.

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Visit us at:
www.suragus.com
www.sheet-resistance-testing.com
www.suragus.com/calculator

Engineered and Made in Germany 



Materials

- ▶ Silicon carbide (SiC)
- ▶ Gallium nitride (GaN)
- ▶ GaAs, AlN and other

Stages

- ▶ Boule
- ▶ Puck
- ▶ Wafer

Benefits

- ▶ Non-contact
- ▶ Mapping / Imaging
- ▶ High sample rate

Measurements

- ▶ Resistivity [$\text{m}\Omega\cdot\text{cm}$]
- ▶ Integrity / effects / defects / facet location
- ▶ Metal layer thickness / sheet resistance

Processes

- ▶ Seed to crystal / boule to puck / puck to wafer
- ▶ Incoming, outgoing inspection, sorting
- ▶ Metalization

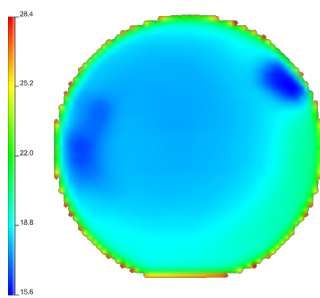
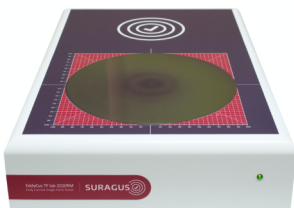
Setups

- ▶ Benchtop tools
- ▶ Sensors for tool integration
- ▶ C2C tools

Solutions

Single Point

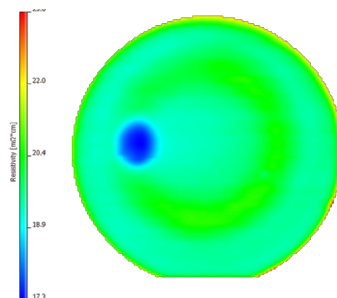
EddyCus® lab Series



Wafer

Imaging

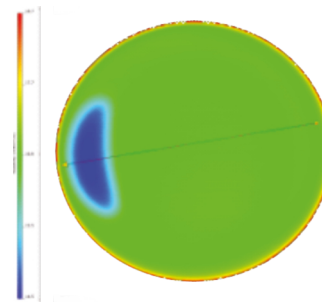
EddyCus® map Series



Wafer

C2C Imaging

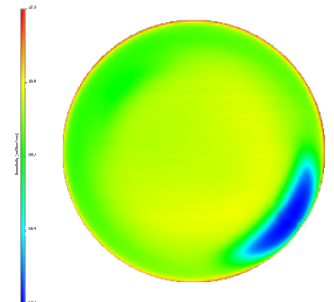
EddyCus® map Series



Puck

Sensors

EddyCus® integration kit XS



Boule